

**REMARKS**

**Claim 10 Amendment.** The sole remaining independent claim 10 is amended, with the amendment being supported at page 6, lines 2-5. The advantages of the new subject matter are set out at page 6, lines 6-20, reading in part, “when the electrode transfer substrate is joined with the semiconductor substrate, the semiconductor substrate and the seed film can be viewed from a rear side of the electrode transfer substrate [and] the electrode transfer substrate can be properly positioned with respect to the semiconductor substrate.” This positioning is also shown in instant Fig. 7 and described at page 14, lines 20-25 and page 15, lines 4-8 and 20-24.

**Transparency.** As the Examiner knows, a metallic film is opaque even when very thin; if so thin that it is partially transparent, it is also so thin that its ability to conduct electrical current is severely limited, so that forming a metal electrode portion (“B” in Figs. 1 and 6) by a process such as electroplating (page 13, line 1) would be impractical. Thus, to the extent that the claimed seed film can easily form a metal electrode portion, it will be opaque.

The alignment of Fig. 7 requires that the substrate be largely transparent. But from the paragraph just above, this requirement precludes the seed film covering the entire substrate. Thus, the feature now added to claim 10, “wherein the seed film is locally present in an area including the metal electrode receiving portion and is absent from other areas of the substrate,” permits the alignment shown in instant Fig. 7, and advances the art.

**The Rejection.** All claims were rejected under §102 over Kawakita '547. This rejection is respectfully traversed.

The rejection asserts that Kawakita's electro-conducting layer 62 anticipates the Applicants' claimed seed layer. However, Kawakita does not meet claim 10 as now amended. Kawakita states that “layer 62 is to be formed on *all over* an insulating layer 61” (column 4, line 56; emphasis added) and there is no disclosure of patterning the layer 62 later, after it is already formed.

Furthermore, Kawakita does not disclose optical alignment of the transfer substrate and the semiconductor substrate; it merely states that they are “aligned” (column 5, line 34 and column 1, line 26), with no elaboration. Thus, transparency of the transfer substrate is not disclosed in this reference, either inherently or overtly.

**New Claims.** New claim 13 explicitly states that the substrate is transparent, supported at page 14, line 20. Referring to Figs. 6A-D and 7, the specification there states, “The glass substrate 21 ... is transparent, so that the semiconductor chip 10 can be seen through a region of the glass substrate not formed with the [metal] seed film portions S.”

This is not disclosed by Kawakita.

Claims 14-15 are supported at page 11, line 9 and page 11, line 14. They are patentable by, *inter alia*, their dependency.

Claim 16 is supported in instant Fig. 4, showing the interconnection film portions W between the seed film portions S. This is described at page 10, line 22. It is also supported in Fig. 2, showing that the electrode connector C is not covered by the patterning film (insulating film 22).

By the present amendment the claims are believed to distinguish over the applied reference. Allowance is requested.

Respectfully submitted,

September 20, 2005  
Date

  
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